50 kPa On-Chip Temperature Compensated and Calibrated Silicon Pressure Sensors

The MPX2050 series devices are silicon piezoresistive pressure sensors providing a highly accurate and linear voltage output, directly proportional to the applied pressure. The sensor is a single, monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation.

Features
• Temperature Compensated Over 0°C to +85°C
• Unique Silicon Shear Stress Strain Gauge
• Easy to Use Chip Carrier Package Options
• Ratiometric to Supply Voltage
• Differential and Gauge Options
• ±0.25% Linearity

Application Examples
• Pump/Motor Controllers
• Robotics
• Level Indicators
• Medical Diagnostics
• Pressure Switching
• Non-Invasive Blood Pressure

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Device Name</th>
<th>Package Options</th>
<th>Case No.</th>
<th># of Ports</th>
<th>Pressure Type</th>
<th>Device Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Unibody Package (MPX2050 Series)</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>MPX2050D</td>
<td>Tray</td>
<td>344</td>
<td>•</td>
<td>Single</td>
<td>MPX2050D</td>
</tr>
<tr>
<td>MPX2050GP</td>
<td>Tray</td>
<td>344B</td>
<td>•</td>
<td>Dual</td>
<td>MPX2050GP</td>
</tr>
<tr>
<td>MPX2050DP</td>
<td>Tray</td>
<td>344C</td>
<td>•</td>
<td>Differential</td>
<td>MPX2050DP</td>
</tr>
<tr>
<td>MPX2050GSX</td>
<td>Tray</td>
<td>344F</td>
<td>•</td>
<td>Absolute</td>
<td>MPX2050D</td>
</tr>
</tbody>
</table>

Application Examples
• Pump/Motor Controllers
• Robotics
• Level Indicators
• Medical Diagnostics
• Pressure Switching
• Non-Invasive Blood Pressure

PACKAGES

MPX2050D CASE 344-15
MPX2050GP CASE 344B-01
MPX2050DP CASE 344C-01
MPX2050GSX CASE 344F-01
Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

Figure 1. Temperature Compensated Pressure Sensor Schematic

**Voltage Output versus Applied Differential Pressure**

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).
### Operating Characteristics

#### Table 1. Operating Characteristics

(V$_S$ = 10 Vdc, T$_A$ = 25°C unless otherwise noted, P$_1$ > P$_2$)

<table>
<thead>
<tr>
<th>Characteristics</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Pressure Range$^{(1)}$</td>
<td>P$_{OP}$</td>
<td>0</td>
<td>—</td>
<td>50</td>
<td>kPa</td>
</tr>
<tr>
<td>Supply Voltage$^{(2)}$</td>
<td>V$_S$</td>
<td>—</td>
<td>10</td>
<td>16</td>
<td>Vdc</td>
</tr>
<tr>
<td>Supply Current</td>
<td>I$_o$</td>
<td>—</td>
<td>6.0</td>
<td>—</td>
<td>mA dc</td>
</tr>
<tr>
<td>Full Scale Span$^{(3)}$</td>
<td>V$_{FSS}$</td>
<td>38.5</td>
<td>40</td>
<td>41.5</td>
<td>mV</td>
</tr>
<tr>
<td>Offset$^{(4)}$</td>
<td>V$_{off}$</td>
<td>-1.0</td>
<td>—</td>
<td>1.0</td>
<td>mV</td>
</tr>
<tr>
<td>Sensitivity</td>
<td>$\frac{\Delta V}{\Delta P}$</td>
<td>—</td>
<td>0.8</td>
<td>—</td>
<td>mV/kPa</td>
</tr>
<tr>
<td>Linearity$^{(5)}$</td>
<td>—</td>
<td>-0.25</td>
<td>—</td>
<td>0.25</td>
<td>%VFSS</td>
</tr>
<tr>
<td>Pressure Hysteresis$^{(5)}$ (0 to 50 kPa)</td>
<td>—</td>
<td>—</td>
<td>±0.1</td>
<td>—</td>
<td>%VFSS</td>
</tr>
<tr>
<td>Temperature Hysteresis$^{(5)}$ (-40°C to +125°C)</td>
<td>—</td>
<td>—</td>
<td>±0.5</td>
<td>—</td>
<td>%VFSS</td>
</tr>
<tr>
<td>Temperature Effect on Full Scale Span$^{(5)}$</td>
<td>TCV$_{FSS}$</td>
<td>-1.0</td>
<td>—</td>
<td>1.0</td>
<td>%VFSS</td>
</tr>
<tr>
<td>Temperature Effect on Offset$^{(5)}$</td>
<td>TCV$_{off}$</td>
<td>-1.0</td>
<td>—</td>
<td>1.0</td>
<td>mV</td>
</tr>
<tr>
<td>Input Impedance</td>
<td>Z$_{in}$</td>
<td>1000</td>
<td>—</td>
<td>2500</td>
<td>Ω</td>
</tr>
<tr>
<td>Output Impedance</td>
<td>Z$_{out}$</td>
<td>1400</td>
<td>—</td>
<td>3000</td>
<td>Ω</td>
</tr>
<tr>
<td>Response Time$^{(6)}$ (10% to 90%)</td>
<td>t$_R$</td>
<td>—</td>
<td>1.0</td>
<td>—</td>
<td>ms</td>
</tr>
<tr>
<td>Warm-Up</td>
<td>—</td>
<td>—</td>
<td>20</td>
<td>—</td>
<td>ms</td>
</tr>
<tr>
<td>Offset Stability$^{(7)}$</td>
<td>—</td>
<td>—</td>
<td>±0.5</td>
<td>—</td>
<td>%VFSS</td>
</tr>
</tbody>
</table>

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
3. Full Scale Span (V$_{FSS}$) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V$_{off}$) is defined as the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:
   - Linearity:Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
   - Temperature Hysteresis:Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis:Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - TcSpan:Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.
   - TcOffset:Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Offset stability is the product’s output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.
Maximum Ratings

Table 2. Maximum Ratings

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Maximum Pressure (P1 &gt; P2)</td>
<td>P\text{\textsubscript{max}}</td>
<td>200</td>
<td>kPa</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>T\text{\textsubscript{stg}}</td>
<td>-40 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>T\text{\textsubscript{A}}</td>
<td>-40 to +125</td>
<td>°C</td>
</tr>
</tbody>
</table>

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

LINEARITY

Linearity refers to how well a transducer’s output follows the equation: $V_{\text{out}} = V_{\text{off}} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the “best case” linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the “worst case” error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Motorola’s specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

Figure 2. Linearity Specification Comparison
On-Chip Temperature Compensation and Calibration

Figure 3 shows the minimum, maximum and typical output characteristics of the MPX2050 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on Full-Scale Span and Offset are very small and are shown under Operating Characteristics.

Figure 3. Output versus Pressure Differential

Figure 4. Cross-Sectional Diagram (not to scale)

Figure 4 illustrates the differential or gauge configuration in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2050 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.
Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing the silicone gel which isolates the die. The pressure sensor is designed to operate with positive differential pressure applied, \( P_1 > P_2 \). The Pressure (P1) side may be identified by using the following table.

### Table 3. Pressure (P1) Side Delineation

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Case Type</th>
<th>Pressure (P1) Side Identifier</th>
</tr>
</thead>
<tbody>
<tr>
<td>MPX2050D</td>
<td>344</td>
<td>Stainless Steel Cap</td>
</tr>
<tr>
<td>MPX2050DP</td>
<td>344C</td>
<td>Side with Part Marking</td>
</tr>
<tr>
<td>MPX2050GP</td>
<td>344B</td>
<td>Side with Port Attached</td>
</tr>
<tr>
<td>MPX2050GSX</td>
<td>344F</td>
<td>Side with Port Attached</td>
</tr>
</tbody>
</table>
package Dimensions

NOTES:
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION A IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

<table>
<thead>
<tr>
<th>NOTES:</th>
</tr>
</thead>
<tbody>
<tr>
<td>CONTROLLING DIMENSION: INCH.</td>
</tr>
</tbody>
</table>

| CASE 344-15 |
| ISSUE AA |
| UNIBODY PACKAGE |

| CASE 344B-01 |
| ISSUE B |
| UNIBODY PACKAGE |
PACKAGE DIMENSIONS

NOTES:
2. CONTROLLING DIMENSION: INCH.

CASE 344C-01
ISSUE B
UNIBODY PACKAGE

CASE 344F-01
ISSUE B
UNIBODY PACKAGE

MPX2050
Sensors
Freescale Semiconductor
How to Reach Us:

Home Page:  
www.freescale.com

Web Support:  
http://www.freescale.com/support

USA/Europe or Locations Not Listed:  
Freescale Semiconductor, Inc.  
Technical Information Center, EL516  
2100 East Elliot Road  
Tempe, Arizona 85284  
1-800-521-6274 or +1-480-768-2130  
www.freescale.com/support

Europe, Middle East, and Africa:  
Freescale Halbleiter Deutschland GmbH  
Technical Information Center  
Schatzbogen 7  
81829 Muenchen, Germany  
+44 1296 380 456 (English)  
+46 8 5220080 (English)  
+49 89 92103 559 (German)  
+33 1 69 35 48 48 (French)  
www.freescale.com/support

Japan:  
Freescale Semiconductor Japan Ltd.  
Headquarters  
ARCO Tower 15F  
1-5-1, Shimo-Meguro, Meguro-ku,  
Tokyo 153-0064  
Japanese  
0120 191014 or +81 3 5437 9125  
support.japan@freescale.com

Asia/Pacific:  
Freescale Semiconductor China Ltd.  
Exchange Building 23F  
No. 118 Jianguo Road  
Chaoyang District  
Beijing 100022  
China  
+86 10 5879 8000  
support.asia@freescale.com

For Literature Requests Only:  
Freescale Semiconductor Literature Distribution Center  
P.O. Box 5405  
Denver, Colorado 80217  
1-800-411-2447 or +1-303-675-2140  
Fax: +1-303-675-2150  
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. “Typical” parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including “Typicals”, must be validated for each customer application by customer’s technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners. © Freescale Semiconductor, Inc. 2008. All rights reserved.